

PC/104 Embedded Consortium

www.pc104.org

PCI-104 Specification

Version 1.1

October 13, 2008

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REVISION HISTORY

1.0, Nov, 2003

a. Formatted to meet the requirements of the PC/104 Embedded Consortium.

1.1, October 13, 2008

- a. Changed dates and copyright notice and added Logo to cover
- b. Corrected dimensions in Figure 1. Standoff height is 0.600" (15.24mm)
- c. Added power management signals to Figure 2, following sections, and Table 3
- d. Removed -5V from Table 2 because it is not on the PCI connector
- e. Added standoff mechanical drawing in Appendix C
- f. Figure 4. Added "complementary" to description of Rotary Switch.
- g. Fixed page numbers in TOC, TOF, and TOT

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1. INTRODUCTION

The ISA architecture bus has long been a popular choice for embedded applications. With the publication of the PC/104 standard in 1992, this bus architecture was available on a small, rugged form factor which has since become an industry standard. As technological requirements advanced, a need began to arise for a higher performance bus throughput. This is especially true when it comes to graphics devices as well as other high-speed I/O devices such as networks. The PC/104 Consortium met this challenge by incorporating a PCI bus on the PC/104 form factor, which became to be known as PC/104-*Plus*. This architecture provides a link to versatile legacy hardware while meeting the high-speed requirements for present and future hardware.

To accommodate the gradual replacement of ISA bus devices with PCI devices, the PCI-104 was approved by the PC/104 Consortium. PCI-104 is a PCI-only architecture that accommodates the advances of PCI devices in a small rugged form factor.

This document supplies the mechanical and electrical specifications for the "PCI-104" which has the advantage of the high-speed PCI bus.

1.1 Summary of Key Differences From PC/104 Specification:

- The AT and XT connectors for the ISA bus have been removed.
- The component height on the topside has been reduced from 0.435" to 0.345" and the bottom has been increased from 0.100" to 0.190" to increase the flexibility of the module.
- Control logic added to handle the requirements for the high-speed bus.

1.2 Summary of Key Differences From PC/104-Plus Specification:

• The AT and XT connectors for the ISA bus have been removed.

1.3 Summary of Key Differences (120-pin PCI and PCI Local Bus Specification)

- The PCI bus connector is a 4x30 (120-pin) 2mm pitch stack-through connector as opposed to the 124-pin edge connector on standard 32-bit PCI Local Bus.
- The 120-pin PCI does not support 64-bit Extensions, JTAG, PRSNT, or CLKRUN signals.

1.4 References

This document covers the addition of the PCI functions. The following documents should be used as reference for a detailed understanding of the overall system requirements:

- "PCI and PCI-X Hardware and Software (Architecture and Design Library)" by Edward Solari
- "PCI System Architecture" by MindShare, Inc.
- PCI Local Bus Specification Revision 2.2 by PCI Special Interest Group
- PC/104 Specification by PC/104 Embedded Consortium
- PC/104-Plus Specification by PC/104 Embedded Consortium

Contact the PCI Special Interest Group office for the latest revision of the PCI specification:

PCI Special Interest Group

Email: <u>administration@pcisig.com</u> Website: <u>www.pcisig.com</u>

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PC/104 Embedded Consortium

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2. A POSSIBLE MODULE STACK CONFIGURATION

Figure 1 shows a typical module stack with two PCI-104 modules, one PC/104-*Plus* module, one PC/104 16-bit module, and one PC/104 8-bit module. The maximum configuration for the PCI bus of PC/104-*Plus* modules is four plus the Host Board. If standard PC/104 modules are used in the stack, they must be the top module(s) because they will normally not include the PCI bus.

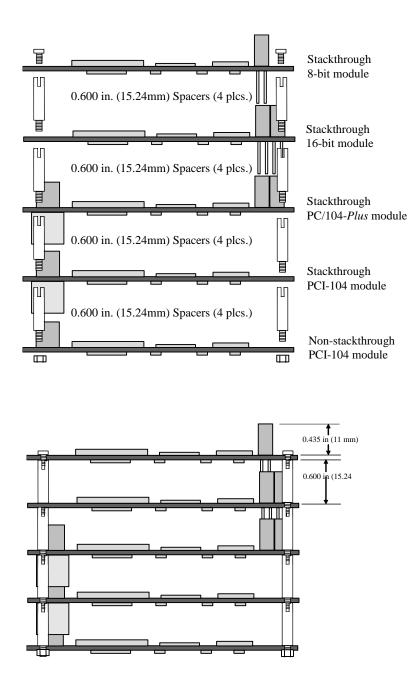


Figure 1: A Possible Module Stack Configuration

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3. PCI SIGNAL DEFINITION

Figure 2 shows the pins in functional groups, with the required pins on the left and the optional pins on the right side. The shaded pins on the right are unsupported features, but are included to show the entire PCI bus as defined in the *PCI Local Bus Specification Revision 2.2*. This version of the PCI bus is intended as a 32-bit bus running at 33MHz and therefore, 64-bit extension and 66MHz¹ are not supported at this time. Also not supported are the boundary scan features (JTAG), *Present* (PRSNT[1:2]#), and *Clock running* (CLKRUN#). The direction indication on the pins assumes a combination master/target device.

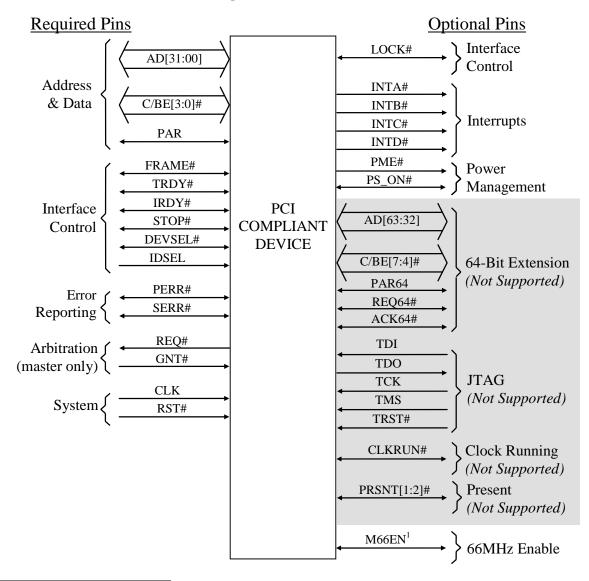


Figure 2: PCI Pin List

¹ The PCI bus has been simulated at 33MHz. For the purpose of this specification, 66MHz is not supported. To support future enhancements, the M66EN signal should be grounded on any module that cannot support 66MHz and left open for modules that can support a 66MHz clock.

3.1 PCI Bus Signal Description

3.1.1 Address and Data

AD[31:00]	Address and Data are multiplexed on the same PCI pins. A bus transaction consists of an address phase followed by one or more data phases.
C/BE[3:0]#	Bus Command/Byte Enables are multiplexed. During the address phase of a transaction, they define the bus command. During the data phase, they are used as byte enables.
PAR	Parity is even parity across AD[31:00] and C/BE[3:0]#. Parity generation is required by all PCI signals.

3.1.2 Interface Control Pins

FRAME#	Cycle Frame is driven by the current master to indicate the beginning of an access and will remain active until the final data cycle.
TRDY#	Target Ready indicates the selected device's ability to complete the current data phase of the transaction. Both IRDY# and TRDY# must be asserted to terminate a data cycle.
IRDY#	Initiator Ready indicates the bus master's ability to complete the current data phase of the transaction.
STOP#	Stop indicates the current selected device is requesting the master to stop the current transaction.
DEVSEL#	Device Select , when actively driven, indicates the driving device has decoded its address as the target of the current access.
IDSEL	Initialization Device Select is used as a chip-select during configuration read and write transactions.
LOCK#	Lock indicates an atomic operation to a bridge that may require multiple transactions to complete.

3.1.3 Error Reporting

PERR#	Parity Error is for reporting data parity errors.
SERR#	System Error is for reporting address parity errors.

3.1.4 Arbitration (Bus Masters Only)

REQ#	Request indicates	to the arbitrate	or that this dev	vice desires use	of the bus.

GNT# Grant indicates to the requesting device that access has been granted.

3.1.5 System

CLK	Clock provides timing for all transactions on the PCI bus and is an input to every PCI device.
RST#	Reset is used to bring PCI-specific registers, sequencers, and signals to a consistent state.
M66EN	66 MHz Enable indicates to a device whether the bus segment is operating at 33 MHz or 66 MHz. The PCI bus has been simulated at 33MHz. For the purpose of this specification, 66MHz is not supported. To support future enhancements, the M66EN signal should be grounded on any module that cannot support 66MHz and left open for modules that can support a 66MHz clock.

3.1.6 Interrupts

INTA#	Interrupt A is used to request Interrupts.
INTB#	Interrupt B is used to request Interrupts.
INTC#	Interrupt C is used to request Interrupts.
INTD#	Interrupt D is used to request Interrupts.

3.1.7 Power Management

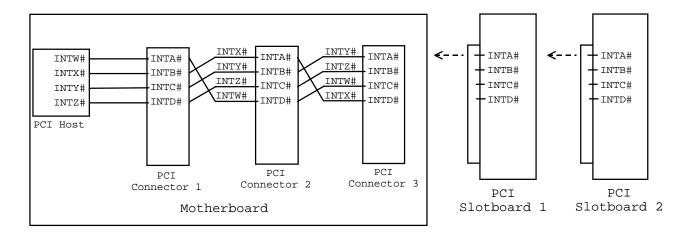
PME#	Power Management Event is used to bring the CPU out of power down states such as wake-on-LAN.
PSON#	Power Supply On is a power supple control signal that can turn the power supply on or off.
+5V_SB	+5 Volt Standby is a power source that is always present when main power is supplied to the system.

3.2 Signal Grouping

The PCI-104 architecture was developed to take advantage of the versatility and simplicity of the PC market for embedded applications. Like the desktop PC, PCI-104 has the ability to add auxiliary boards to expand the capabilities of the CPU. But instead of using slot cards, PCI-104 adds additional modules using stack-through connectors. This has two advantages: it reduces the system size and it makes the system more rugged so that it can better withstand shocks and vibrations.

To realize a stack-through architecture, a means of selecting the appropriate signals for each expansion card must be established that will easily allow for the installation and configuration of add-in PC/104-*Plus* and PCI-104 modules. The signals in question include CLKx, IDSELx, REQx#, GNTx#, and INTx# lines. Normal desktop computers overcome this problem by routing only the necessary signals to each of the slot connectors. For example, on a desktop PC, only CLK1, IDSEL1, REQ1#, and GNT1# are routed to PCI slot 1. Likewise, CLK2, IDSEL2, REQ2#, and GNT2# are routed to slot 2.

The interrupts on a desktop PC are handled in a different manner. All four interrupts from the interrupt controller are routed to each PCI slot connector. By convention INTA# on an expansion card is used for single-function devices and the remaining interrupts are used in the case of multi-functional devices. This could place a large burden on INTA# since all of the expansion cards would use this interrupt. To alleviate the burden, PC manufacturers stagger the interrupts on the motherboard to each of the PCI connectors. This is shown in Figure 3.





Since PCI-104 is a stack-through architecture, there is only one connector to which all of the expansion boards must connect. A means of selecting the appropriate signals must be established that will easily allow for the installation and configuration of add-in PC/104-*Plus* and PCI-104 modules. Figure 4 shows such a method that can be applied to the expansion boards.

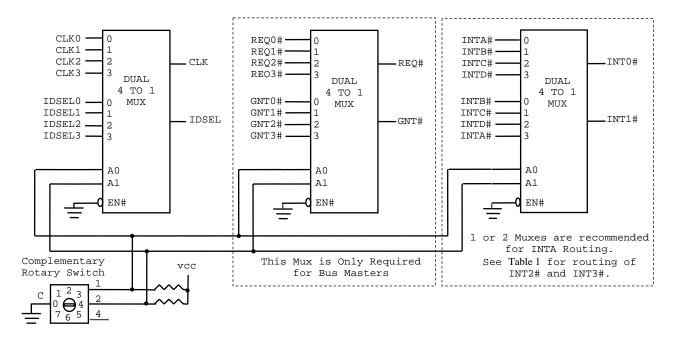


Figure 4: Signal Select on an Expansion Board

The multiplexer chips on the expansion board serve as the equivalent of having multiple PCI slot connectors on the motherboard of a desktop PC. To select the appropriate REQ#, GNT#, CLK, and INT signals for the expansion module, the rotary switch must be adjusted for the position on the stack.

For expansion modules requiring more than one interrupt, the staggering of the INTx# lines is accomplished on the expansion module prior to the multiplexers. Figure 5 shows the interrupt routing on a PCI Host Module and on an expansion module with two functions. The Add-on Module portion of Figure 5 shows how the right-hand multiplexer of Figure 4 fits onto an add-on module. If a board has a single function then only half of the multiplexer is required.

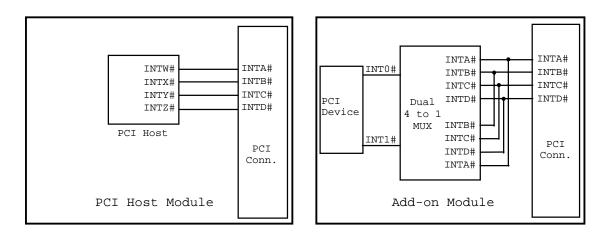


Figure 5: INT# Select

The multiplexer chips are Dual 4:1 Mux/Demux chips. They provide a 5Ω switch that connects the input and output together. These switches provide a bi-directional path with no signal propagation delay other than the RC delay of the on resistance of the switch and the load capacitance. This is typically 250ps at 50pF load. Use one Mux for 1 to 2 interrupts or two Muxes for 3 to 4 interrupts.

While other methods of configuring the modules are possible and permissible, the rotary switch is clean and provides for the least possible error in configuration.

Table 1 shows the appropriate switch setting and signals used for each module in the stack.

Switch Position	Module Slot	REQ#	GNT#	CLK	INT0#	INT1#	INT2#	INT3#
0 or 4	1	REQ0#	GNT0#	CLK0	INTA#	INTB#	INTC#	INTD#
1 or 5	2	REQ1#	GNT1#	CLK1	INTB#	INTC#	INTD#	INTA#
2 or 6	3	REQ2#	GNT2#	CLK2	INTC#	INTD#	INTA#	INTB#
3 or 7	4	REQ3#	GNT3#	CLK3	INTD#	INTA#	INTB#	INTC#

Table 1: Rotary Switch Settings

3.3 +5V_SB, PSON#, and PME#

To support ATX power supplies and power down features three signals have been added to the PCI bus. They are $+5V_SB$ which is a power source that is always present when main power is supplied to the system, PSON#

which is a power supply control signal that can turn the power supple on or off, and PME# which can be used to bring the CPU out of power down states such as wake-on-LAN.

These signals have been implemented on the reserved pins of the PCI expansion bus of the PC/104-*Plus* and PCI-104 Specifications at pins B1, C9, and D10. Not all manufacturers will implement these signals; therefore to maintain compatibility with existing products it is important for designs that implement these functions to protect against undriven inputs.

4. ELECTRICAL SPECIFICATION

4.1 PCI Bus

The PCI Bus mechanical interface is a stackable 4x30 header. This interface carries all of the required PCI signals per *PCI Local Bus Specification Revision 2.2*.

4.1.1 Signal Definitions

For full details on the electrical requirements for the PCI bus, reference the *PCI Local Bus Specification Revision 2.2.*

4.1.2 Signal Assignments

Signals are assigned in the same relative order as in the *PCI Local Bus Specification Revision 2.2*, but transformed to the corresponding header connector pins. Because of the stack-through nature of the bus, slot-specific signals are duplicated for each plug-in module. The system has been designed to accommodate 4 modules, which are PC/104-*Plus*, PCI-104, or a combination of the two, so multiple sets of the signals have been duplicated to accommodate one signal for each module. These four signal groups include: IDSEL[3:0], CLK[3:0], REQ#[3:0], GNT#[3:0]. Signal assignments for the J3/P3 connector are given in Appendix B, Table 3: PCI Bus Signal Assignments.

4.1.3 Power and Ground Pins

The total number of power and ground signals remains the same, but the +3.3 V pins have been reduced by two and the ground pins have been increased by two. The change was the result of signal grouping on the bus and has no effect on performance or integrity.

4.1.4 AC/DC Signal Specifications

All bus timing and signal levels are identical to the *PCI Local Bus Specification Revision* 2.2.

4.2 Module Power Requirements

Table 2 specifies the voltage and maximum power requirements for each PCI-104 module. Care should be used in designing PCI-104 modules to guarantee the least possible power consumption. A worst-case module as specified could use almost 39 Watts of power, which would be unacceptable in most systems.

Supply	Min. Voltage	Max. Voltage	Max. Current	Max. Power
+3.3V	+3.3V 3.00		3A	10.8W
+5V	4.75	5.25	2A	10.5W
+12V	11.4	12.6	1A	12.6W
-12V	-12.6	-11.4	0.3A	3.78W
+5V_SB	4.75	5.25	1.0A	5W

Table 2:	Module	Power	Rea	uirements
10010 10	1110 a date		1100	

Note 1: Host Boards implementing "5 volt PCI signaling" are not required to supply 3.3 volts to the modules, but must provide a bus and decoupling. Host Boards implementing "3.3 volt PCI signaling" are not required to supply 5 volts to the modules, but must provide a bus and decoupling.

4.3 PCI Signaling Voltage (VI/O) Requirements

4.3.1 PCI Host Module

The PCI Host board will always determine the PCI signaling level on the bus by setting all VI/O pins to either 3.3V or 5V. If VI/O is set to 3.3V, then the system will use 3.3V I/O signaling and, likewise, if VI/O is set to 5V, then the system will use 5V I/O signaling. Some PCI host modules may only allow one of the options, while others may provide a jumper to allow the user to select the signaling level. Once the signaling level is selected, the remaining boards in the system must use that signaling level.

4.3.2 Add-In Modules

Add-in cards can be 3.3V, 5V, or universal.

3.3V Add-In Modules

3.3V add-in cards can only operate in environments where VI/O has been set to 3.3V by the PCI Host module. Using 5V add-in modules on a 3.3V stack will result in the 3.3V modules being damaged.

5V Add-In Modules

5V add-in cards operate in environments where VI/O has been set to 5V by the PCI Host module. Using 3.3V add-in modules on a 5V stack will result in the 3.3V modules being damaged.

Universal Add-In Modules

Universal add-in board can be used on either 3V or 5V I/O signaling buses. Universal boards either use the VI/O signal to determine its signaling level or are 3V signaling boards that have 5V-tolerant I/O. Many PCI interface chips have a "VI/O" pin that is the power for the I/O buffers that can be directly connected to VI/O. Universal boards will work on either 3V or 5V I/O signaling buses.

5. LEVELS OF CONFORMANCE

This section provides terminology intended to assist manufacturers and users of PCI-104 buscompatible products in defining and specifying conformance with the PCI-104 Specification.

5.1 PCI-104 "Compliant"

This refers to "PCI-104 form-factor" devices that conform to all non-optional aspects of the PCI-104 Specification, including both *mechanical* and *electrical* specifications.

5.2 PCI-104 "Bus-compatible"

This refers to devices, which are not "PCI-104 form-factor" (i.e., do not comply with the module dimensions of the PCI-104 Specification), but provide male or female PCI-104 bus connectors that meet both the *mechanical* and *electrical* specifications provided for the PCI-104 bus connectors.

6. MECHANICAL SPECIFICATION

6.1 Clock Trace Lengths

The clocks are tuned on the Host Board such that the length of CLK3 trace is ≈ 0.662 " less than CLK2, CLK2 trace is ≈ 0.662 " less than CLK1, and CLK1 trace is ≈ 0.662 " less than CLK0. Therefore, the first module on the stack must select CLK0 (the longest trace), the second CLK1, etc. This provides almost no clock skew between modules. Trace length limits are as indicated in the *PCI Local Bus Specification Revision 2.2*.

6.2 Module Dimensions

The mechanical dimensions for this module are identical to PC/104-*Plus* Specification with the exception of the removed ISA connectors and some modifications to the I/O connector area. The component height on the topside is 0.345" and the bottom side is 0.190". Exceptions to this are the regions along the sides of the module (indicated by the dotted regions in Figure 6) which have height restrictions of 0.435" for the topside and 0.100" for the bottom side. The mechanical dimensions and restrictions are given in Appendix A, Figure 6: PCI-104 Module Dimensions.

6.3 Connector and Shroud

The connector for the PCI bus is a 4x30 (120-pin) 2mm pitch connector. The shroud should be installed on the bottom of the PC board when a stack-through connector is used. The mechanical dimensions and restrictions for the PCI connector are given in Appendix A, Figure 7: PCI Connector, and in Figure 8: PCI Connector Shroud. The shroud should be properly marked to identify the PCI signaling capability of the board (see Section 6.4 Board Identifier).

6.4 Board Identifier

Manufacturers of PCI-104 modules must clearly label, near or on the PCI connector the module's PCI signaling capabilities. The label is to guarantee proper module installation. Depending on the type of board manufactured, the label will be one of the following:

3.3V only 5V only

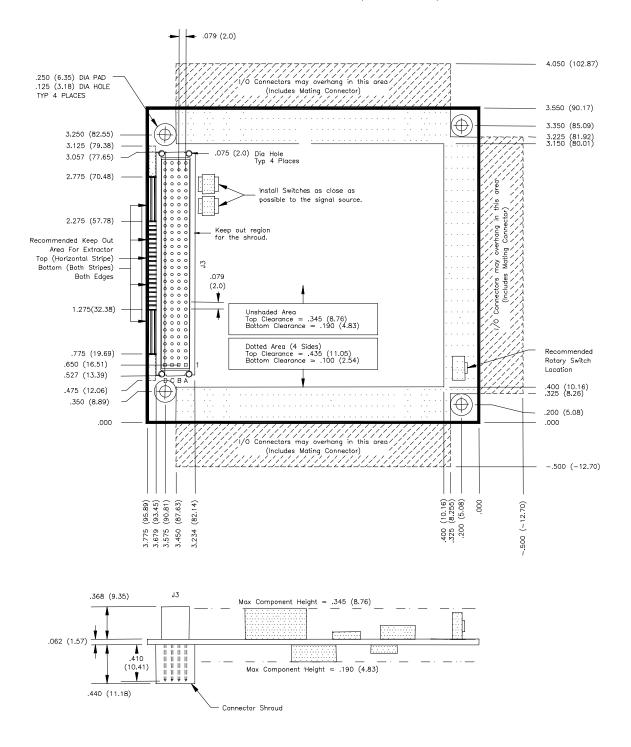
Universal

APPENDIX A

MECHANICAL DIMENSIONS

Figure 6: PCI-104 Module Dimensions

Dimensions are in inches / (millimeters)



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Figure 7: PCI Connector

NOTES: PRESS FIT COMPLIANT PINS PER IEC 352-5 CAN BE USED INSTEAD OF SQUARE PINS AS SHOWN.

2 CONFIGURATION CAN BE MADE OF ONE OR MORE PIECES.

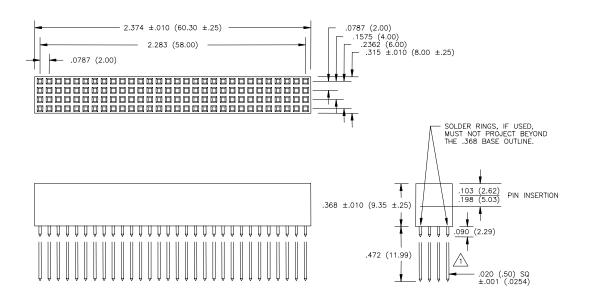
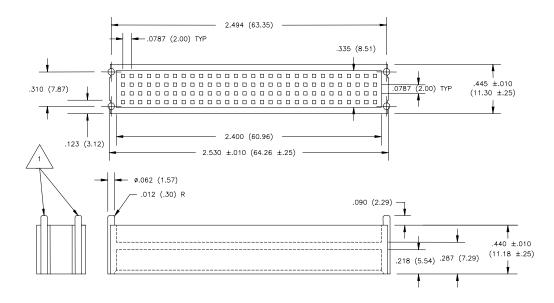


Figure 8: PCI Connector Shroud





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Figure 9: PCI Connector Specifications

Materials

Housing: Contact: Solder: Solder Clip:

Contact Finish

Female Interface: Male Interface: Solder Tail: Underplate:

Mechanical Performance

Insertion Force: Withdrawal Force: Normal Force: Durability: Operating Temp:

Electrical Performance

Contact Resistance: Current Capacity: Dielectric Strength: Insulation Resistance: High Temp Thermoplastic, UL Rated 94-V0 Phosphor Bronze Tin-Lead (63-37), If Applicable Aluminum Alloy, If Applicable

15 Microinches Minimum Hard GoldGold Flash Minimum100 Microinches Minimum Solder50 Microinches Minimum Nickel

2.5 Ounce Per Pin Maximum
1 Ounce Per Pin Minimum
50 Grams Minimum (Per Beam)
50 Cycles Minimum
-55° C To +85° C Minimum

<30 Milliohms Maximum 1 Amp Continuous Per Pin 500 Vac 5,000 Megohms Minimum

APPENDIX B

BUS SIGNAL ASSIGNMENTS

J3/P3						
Pin	Α	В	С	D		
1	GND	$+5V_SB$	+5V	AD00		
2	VI/O	AD02	AD01	+5V		
3	AD05	GND	AD04	AD03		
4	C/BE0#	AD07	GND	AD06		
5	GND	AD09	AD08	GND		
6	AD11	VI/O	AD10	M66EN		
7	AD14	AD13	GND	AD12		
8	+3.3V	C/BE1#	AD15	+3.3V		
9	SERR#	GND	PSON#	PAR		
10	GND	PERR#	+3.3V	PME#		
11	STOP#	+3.3V	LOCK#	GND		
12	+3.3V	TRDY#	GND	DEVSEL#		
13	FRAME#	GND	IRDY#	+3.3V		
14	GND	AD16	+3.3V	C/BE2#		
15	AD18	+3.3V	AD17	GND		
16	AD21	AD20	GND	AD19		
17	+3.3V	AD23	AD22	+3.3V		
18	IDSEL0	GND	IDSEL1	IDSEL2		
19	AD24	C/BE3#	VI/O	IDSEL3		
20	GND	AD26	AD25	GND		
21	AD29	+5V	AD28	AD27		
22	+5V	AD30	GND	AD31		
23	REQ0#	GND	REQ1#	VI/O		
24	GND	REQ2#	+5V	GNT0#		
25	GNT1#	VI/O	GNT2#	GND		
26	+5V	CLK0	GND	CLK1		
27	CLK2	+5V	CLK3	GND		
28	GND	INTD#	+5V	RST#		
29	+12V	INTA#	INTB#	INTC#		
30	-12V	REQ3#	GNT3#	GND		

Table 3: PCI Bus Signal Assignments

Note: 1. The shaded area denotes power or ground signals.

APPENDIX C

Standoff

Standoffs are used to ensure stacked boards retain their connectivity. The standoffs are preferably made from stainless-steel to provide for maximum strength and height tolerance. Pads must be provided for the standoffs, with the same plating as the pads for the connectors.

All critical dimensions are listed. It is up to the user to define the thread typed. The height of the standoff shall be 0.600° +/- 0.005° . The width of the standoff must be able to fit on the Standoff pad called out on the Board Layout & Dimensions Section. The width of the threaded section must be able to fit into the standoff pad hole called out in the Board Layout & Dimensions Section.

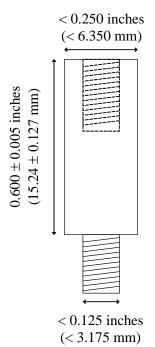


Figure 10: Standoff Mechanical Dimensions